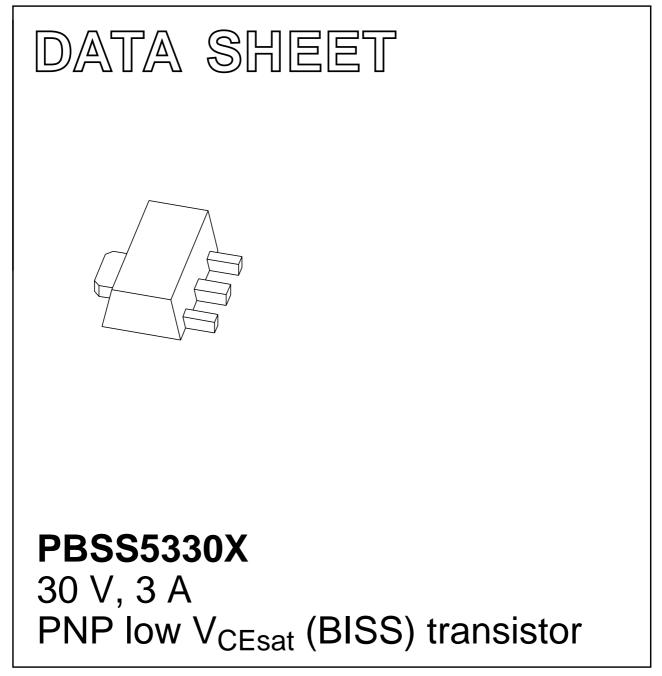
## DISCRETE SEMICONDUCTORS



Product specification Supersedes data of 2003 Nov 28 2004 Nov 03



**PBSS5330X** 

## 30 V, 3 A PNP low V<sub>CEsat</sub> (BISS) transistor

### FEATURES

- SOT89 (SC-62) package
- Low collector-emitter saturation voltage V<sub>CEsat</sub>
- High collector current capability:  $I_C$  and  $I_{CM}$
- Higher efficiency leading to less heat generation
- Reduced printed-circuit board requirements.

#### APPLICATIONS

- Power management
  - DC/DC converters
  - Supply line switching
  - Battery charger
  - LCD backlighting.
- Peripheral drivers
  - Driver in low supply voltage applications (e.g. lamps and LEDs)
  - Inductive load driver (e.g. relays, buzzers and motors).

### DESCRIPTION

PNP low V<sub>CEsat</sub> transistor in a SOT89 plastic package.

#### MARKING

TYPE NUMBER	MARKING CODE <sup>(1)</sup>
PBSS5330X	*1S

#### Note

- 1. \* = p: Made in Hong Kong.
  - \* = t: Made in Malaysia.
    - \* = W: Made in China.

#### **ORDERING INFORMATION**

TYPE NUMBER	PACKAGE				
ITPE NUMBER	NAME	DESCRIPTION	VERSION		
PBSS5330X	SC-62 plastic surface mounted package; collector pad for good heat transfer; 3 leads		SOT89		

#### QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	UNIT
V <sub>CEO</sub>	collector-emitter voltage	-30	V
I <sub>C</sub>	collector current (DC) –3		A
I <sub>CM</sub>	CM peak collector current -5		A
R <sub>CEsat</sub>	equivalent on-resistance	107 mΩ	

### PINNING

PIN	DESCRIPTION	
1	emitter	
2	collector	
3	base	

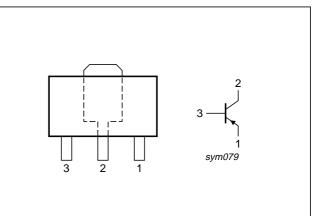


Fig.1 Simplified outline (SOT89) and symbol.

## PBSS5330X

#### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter	-	-30	V
V <sub>CEO</sub>	collector-emitter voltage	open base	-	-30	V
V <sub>EBO</sub>	emitter-base voltage	open collector	-	-6	V
I <sub>C</sub>	collector current (DC)	note 4	-	-3	A
I <sub>CM</sub>	peak collector current	limited by T <sub>j(max)</sub>	-	-5	A
I <sub>B</sub>	base current (DC)		-	-0.5	A
P <sub>tot</sub>	total power dissipation	$T_{amb} \le 25 \ ^{\circ}C$			
		note 1	_	550	mW
		note 2	_	1	W
		note 3	_	1.4	W
		note 4	_	1.6	W
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		-	150	°C
T <sub>amb</sub>	ambient temperature		-65	+150	°C

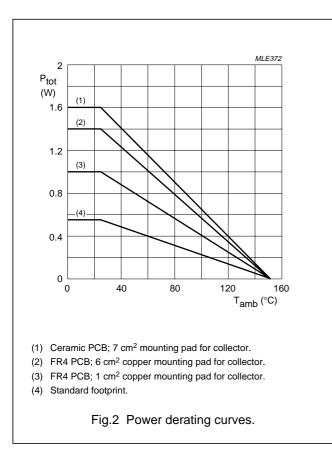
#### Notes

1. Device mounted on a FR4 printed-circuit board; single-sided copper; tin-plated; standard footprint.

2. Device mounted on a FR4 printed-circuit board; single-sided copper; tin-plated; mounting pad for collector 1 cm<sup>2</sup>.

3. Device mounted on a FR4 printed-circuit board; single-sided copper; tin-plated; mounting pad for collector 6 cm<sup>2</sup>.

4. Device mounted on a ceramic printed-circuit board 7 cm<sup>2</sup>, single-sided copper, tin-plated.



## PBSS5330X

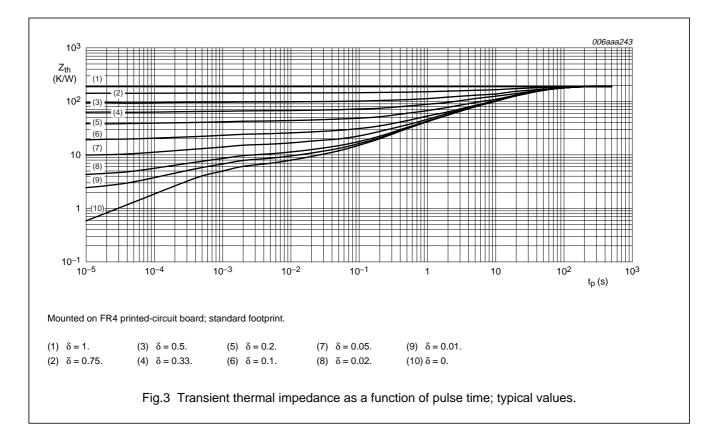
## PBSS5330X

### THERMAL CHARACTERISTICS

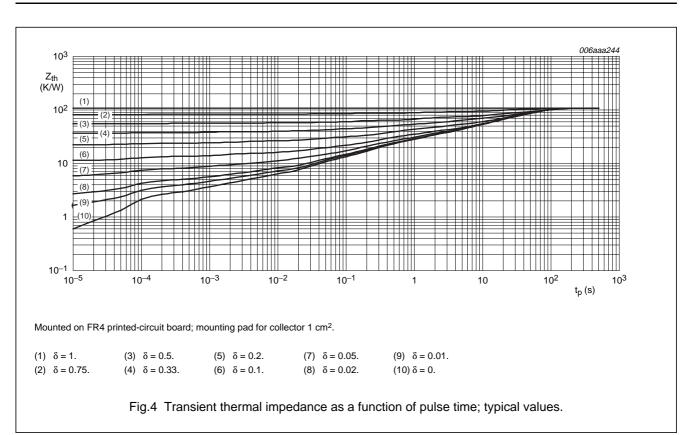
SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient	in free air		
		note 1	225	K/W
		note 2	125	K/W
		note 3	90	K/W
		note 4	80	K/W
R <sub>th(j-s)</sub>	thermal resistance from junction to soldering point		16	K/W

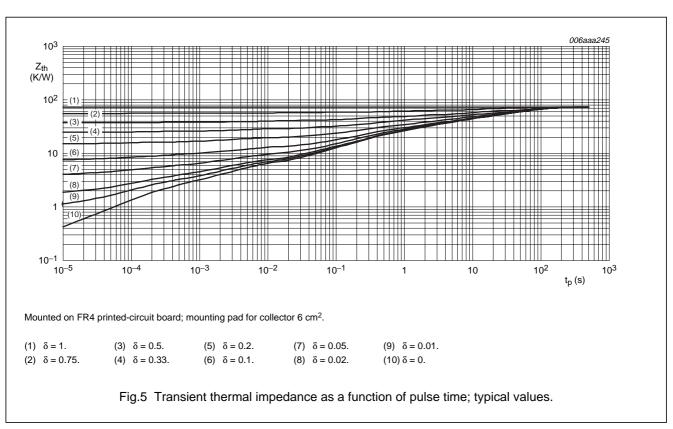
#### Notes

- 1. Device mounted on a FR4 printed-circuit board; single-sided copper; tin-plated; standard footprint.
- 2. Device mounted on a FR4 printed-circuit board; single-sided copper; tin-plated; mounting pad for collector 1 cm<sup>2</sup>.
- 3. Device mounted on a FR4 printed-circuit board; single-sided copper; tin-plated; mounting pad for collector 6 cm<sup>2</sup>.
- 4. Device mounted on a ceramic printed-circuit board 7 cm<sup>2</sup>, single-sided copper, tin-plated.



## PBSS5330X





# 30 V, 3 A PNP low V<sub>CEsat</sub> (BISS) transistor

## PBSS5330X

### CHARACTERISTICS

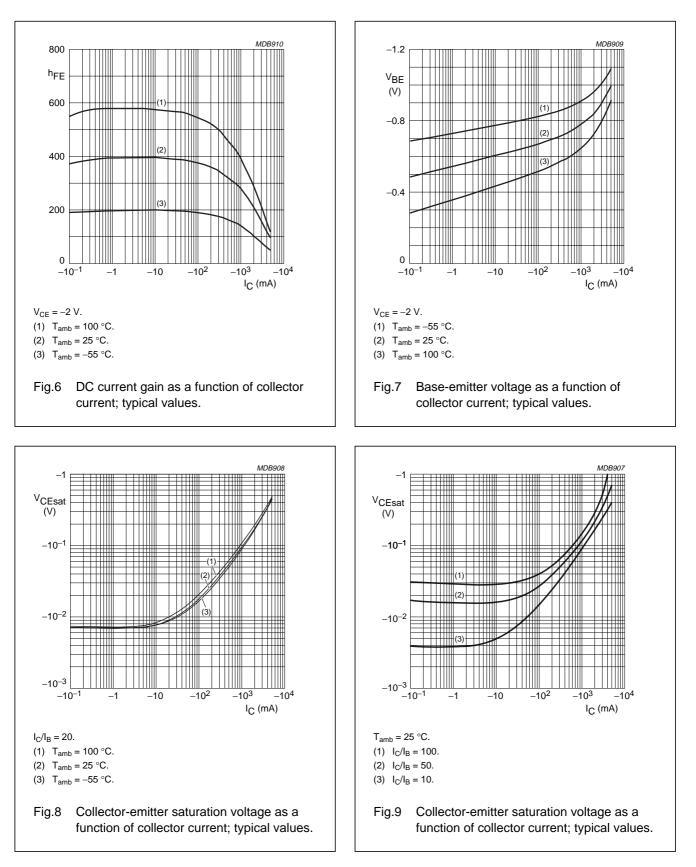
 $T_{amb}$  = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I <sub>CBO</sub>	collector-base cut-off current	$V_{CB} = -30 \text{ V}; \text{ I}_{E} = 0 \text{ A}$	-	-	-100	nA
		$V_{CB} = -30 \text{ V}; \text{ I}_{E} = 0 \text{ A}; \text{ T}_{j} = 150 ^{\circ}\text{C}$	-	-	-50	μA
I <sub>CES</sub>	collector-emitter cut-off current	$V_{CE} = -30 \text{ V}; \text{ V}_{BE} = 0 \text{ V}$	_	-	-100	nA
I <sub>EBO</sub>	emitter-base cut-off current	$V_{EB} = -5 \text{ V}; \text{ I}_{C} = 0 \text{ A}$	-	-	-100	nA
h <sub>FE</sub>	DC current gain	$V_{CE} = -2 V$				
		$I_{\rm C} = -0.1  {\rm A}$	200	-	-	
		$I_{\rm C} = -0.5  {\rm A}$	200	_	_	
		I <sub>C</sub> = -1 A; note 1	175	_	450	
		I <sub>C</sub> = -2 A; note 1	140	_	_	
		I <sub>C</sub> = -3 A; note 1	100	_	_	
V <sub>CEsat</sub>	collector-emitter saturation	$I_{\rm C} = -0.5 \text{ A}; I_{\rm B} = -50 \text{ mA}$	_	-	-70	mV
	voltage	$I_{\rm C} = -1$ A; $I_{\rm B} = -50$ mA	-	-	-130	mV
		$I_{\rm C} = -2$ A; $I_{\rm B} = -100$ mA	_	_	-240	mV
		$I_{C} = -3 \text{ A}; I_{B} = -300 \text{ mA}; \text{ note } 1$	_	-	-320	mV
R <sub>CEsat</sub>	equivalent on-resistance	$I_{C} = -3 \text{ A}; I_{B} = -300 \text{ mA}; \text{ note } 1$	_	80	107	mΩ
V <sub>BEsat</sub>	base-emitter saturation voltage	$I_{\rm C} = -2$ A; $I_{\rm B} = -100$ mA	_	-	-1.1	V
		$I_{C} = -3 \text{ A}; I_{B} = -300 \text{ mA}; \text{ note } 1$	_	-	-1.2	V
V <sub>BEon</sub>	base-emitter turn-on voltage	$V_{CE} = -2 \text{ V}; \text{ I}_{C} = -1 \text{ A}$	-1.0	-	-	V
f <sub>T</sub>	transition frequency	$I_{C} = -100 \text{ mA}; V_{CE} = -5 \text{ V};$ f = 100 MHz	100	-	-	MHz
C <sub>c</sub>	collector capacitance	$V_{CB} = -10 \text{ V}; \text{ I}_{E} = \text{i}_{e} = 0 \text{ A}; \text{ f} = 1 \text{ MHz}$	-	-	45	pF

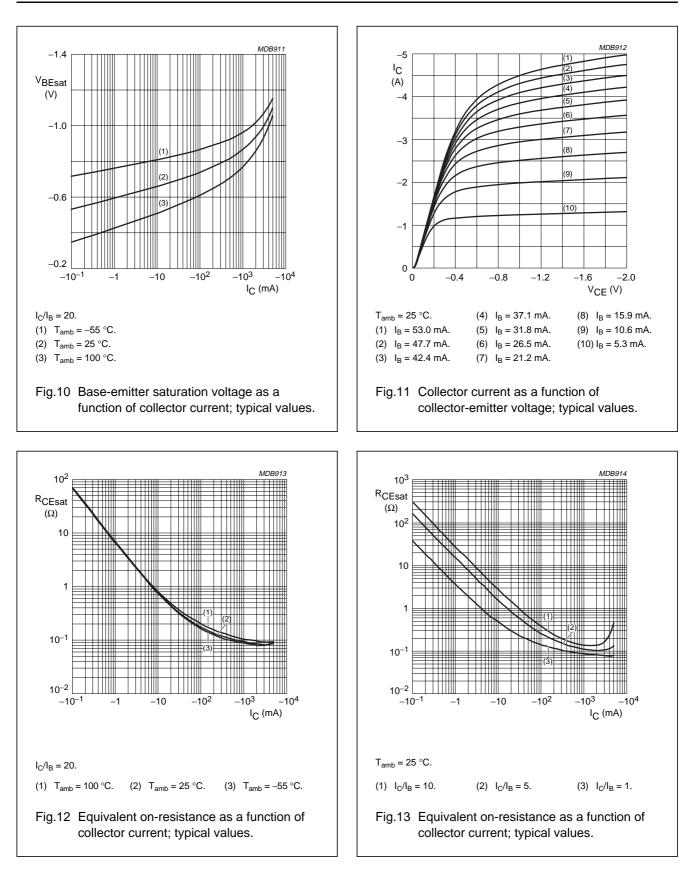
#### Note

1. Pulse test:  $t_p \leq 300 \ \mu s; \ \delta \leq 0.02.$ 

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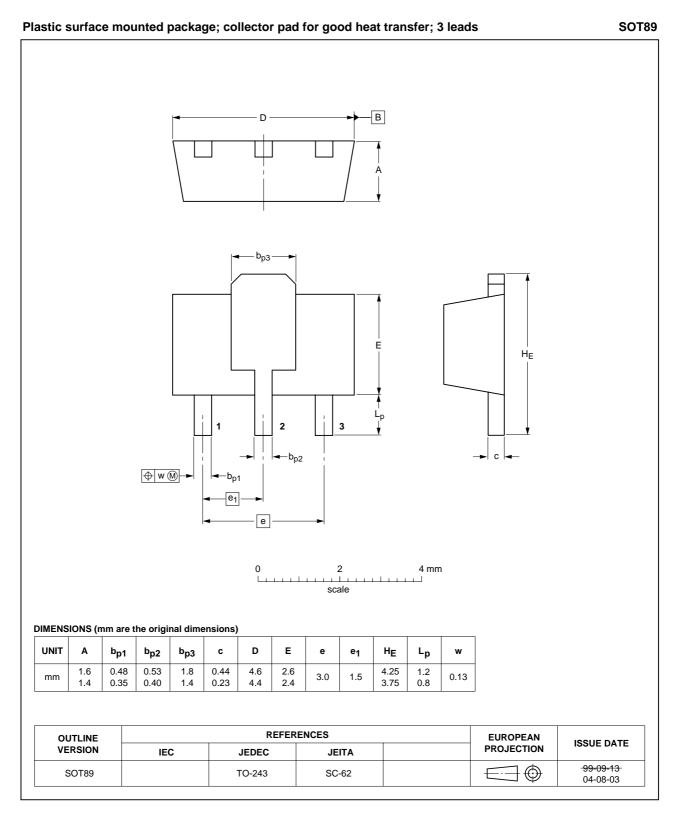
## PBSS5330X



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## PBSS5330X

### PACKAGE OUTLINE



## PBSS5330X

### DATA SHEET STATUS

LEVEL	DATA SHEET STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)(3)</sup>	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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